



Description

JMT N-channel Enhancement Mode Power MOSFET

Features

- 40V, 210A
 $R_{DS(ON)} < 1.6\text{m}\Omega$ @ $V_{GS} = 10\text{V}$
 $R_{DS(ON)} < 3.0\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

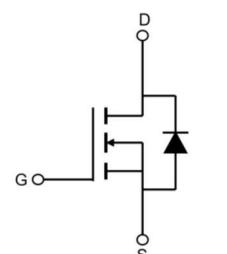
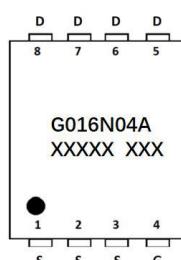
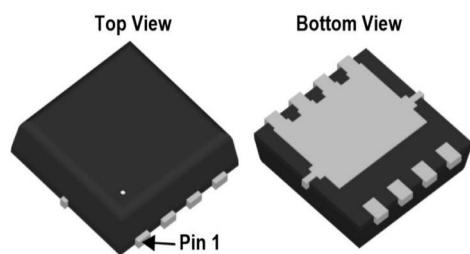
Application

- Load Switch
- PWM Application
- Power management



100% UIS TESTED!

100% ΔV_{ds} TESTED!



PDFN5X6-8L

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
G016N04A	JMTG016N04A	TAPING	PDFN5-8L	13inch	2500	25000

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		40	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	210	A
		$T_C = 100^\circ\text{C}$	137	A
I_{DM}	Pulsed Drain Current ^{note1}		840	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		420	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	120	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.0	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.7	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	-	1.2	1.6	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=20\text{A}$	-	2.1	3.0	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	14.7	-	nF
C_{oss}	Output Capacitance		-	843	-	pF
C_{rss}	Reverse Transfer Capacitance		-	830	-	pF
Q_g	Total Gate Charge	$V_{DS}=20\text{V}$, $I_D=30\text{A}$, $V_{GS}=10\text{V}$	-	95	-	nC
Q_{gs}	Gate-Source Charge		-	15	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	19	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=20\text{V}$, $I_D=30\text{A}$, $R_{\text{GEN}}=3\Omega$, $V_{GS}=10\text{V}$	-	13	-	ns
t_r	Turn-on Rise Time		-	9	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	101	-	ns
t_f	Turn-off Fall Time		-	15	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	210	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	840	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=30\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_{SD}=30\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	-	35	ns
Qrr	Body Diode Reverse Recovery Charge		-	-	24.2	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{GS}=35\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=41\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

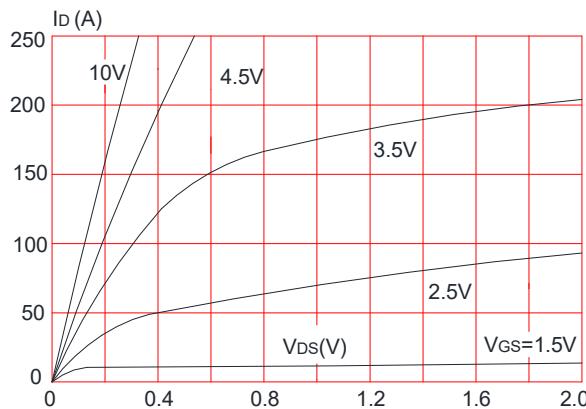


Figure 3: On-resistance vs. Drain Current

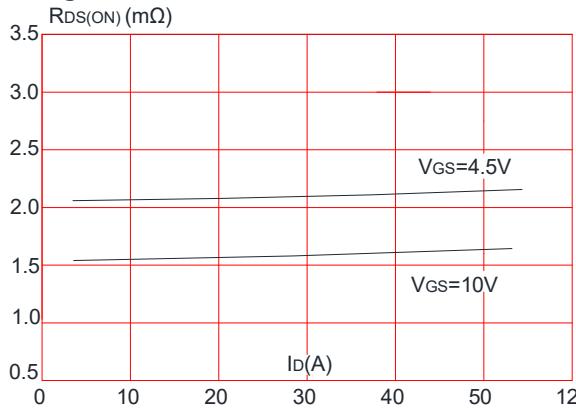


Figure 5: Gate Charge Characteristics

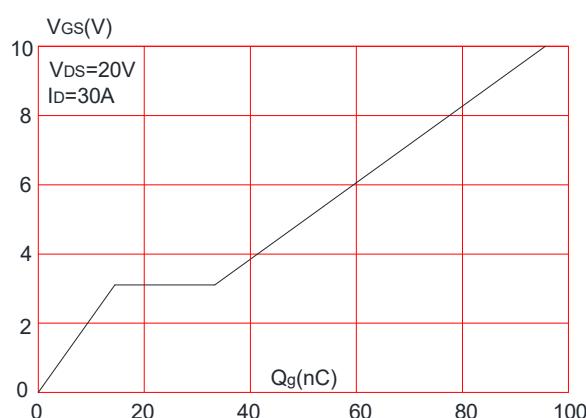


Figure 2: Typical Transfer Characteristics

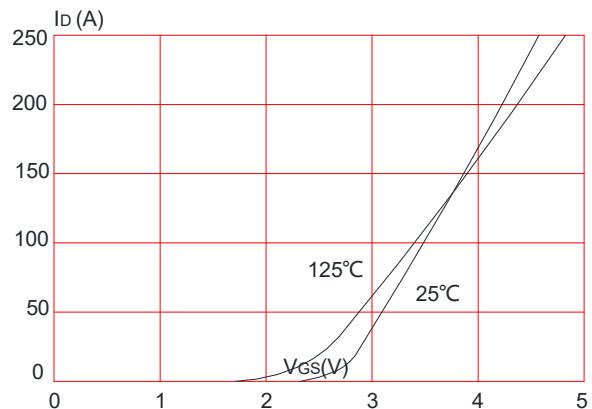


Figure 4: Body Diode Characteristics

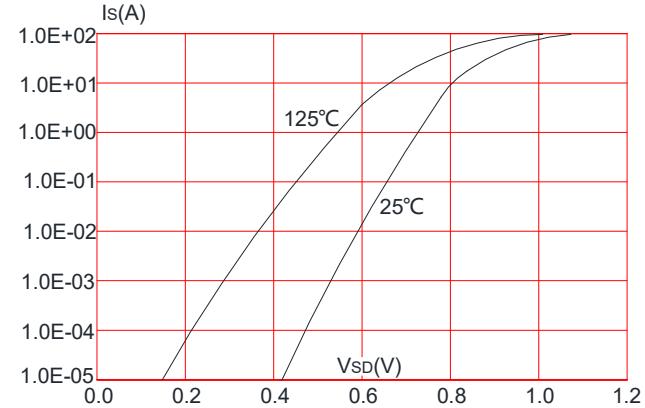


Figure 6: Capacitance Characteristics

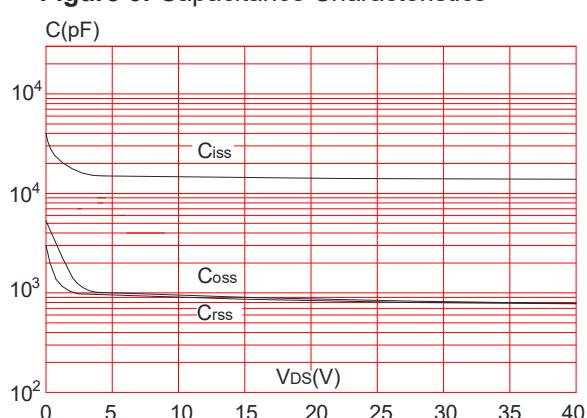


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

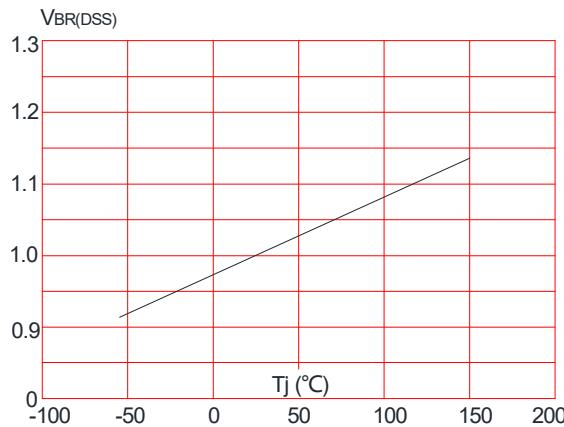


Figure 8: Normalized on Resistance vs. Junction Temperature

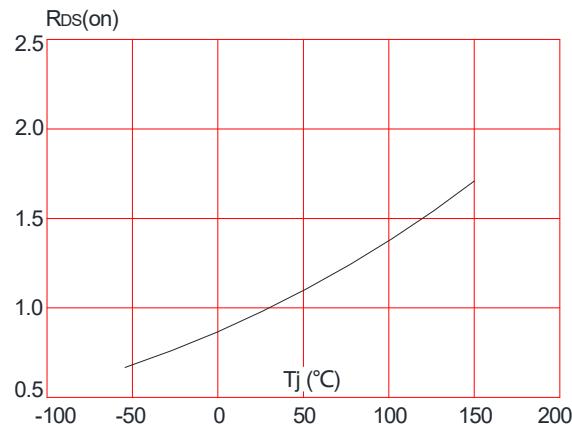


Figure 9: Maximum Safe Operating Area

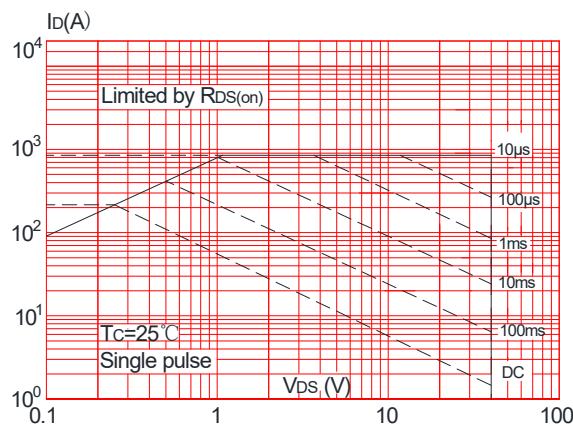


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

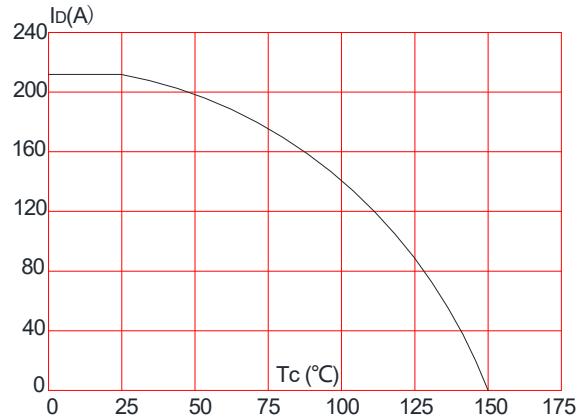
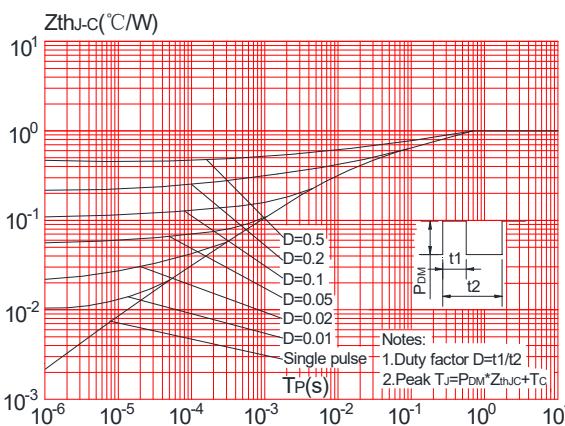


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Test Circuit

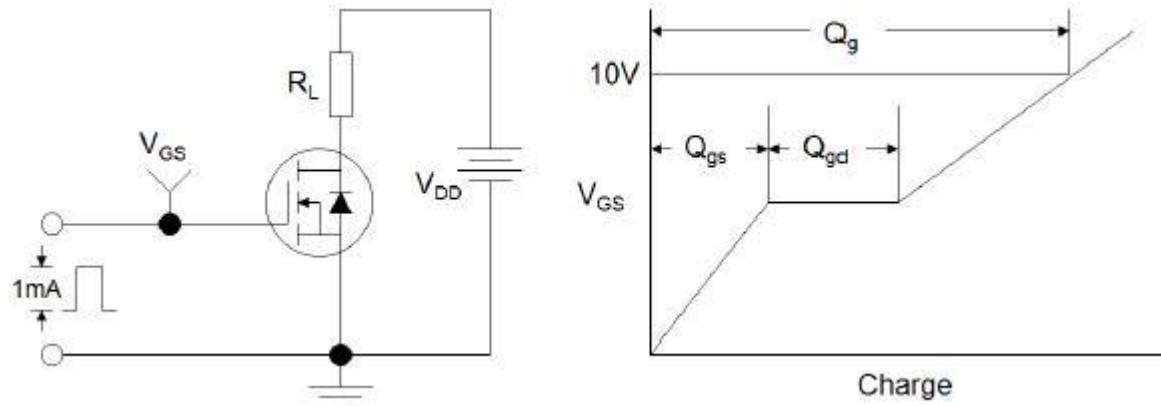


Figure1:Gate Charge Test Circuit & Waveform

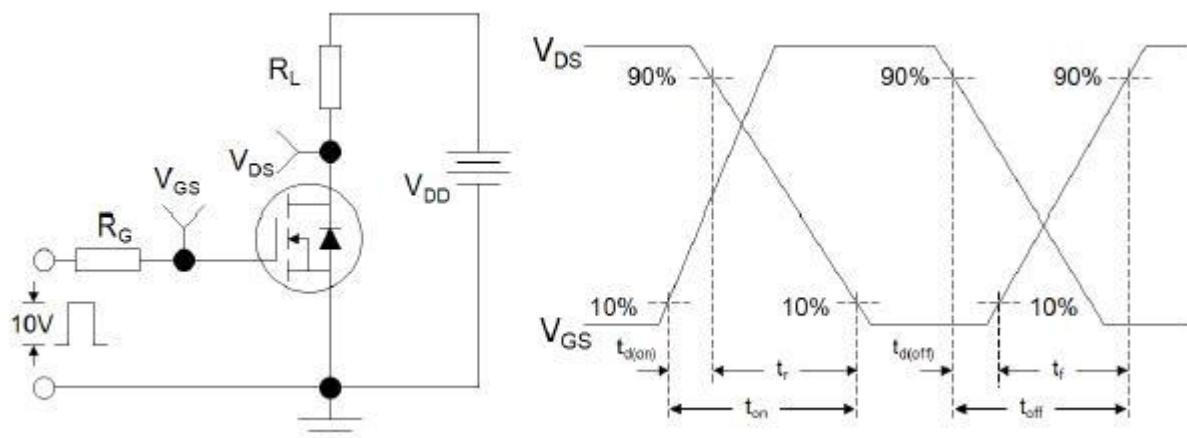


Figure 2: Resistive Switching Test Circuit & Waveforms

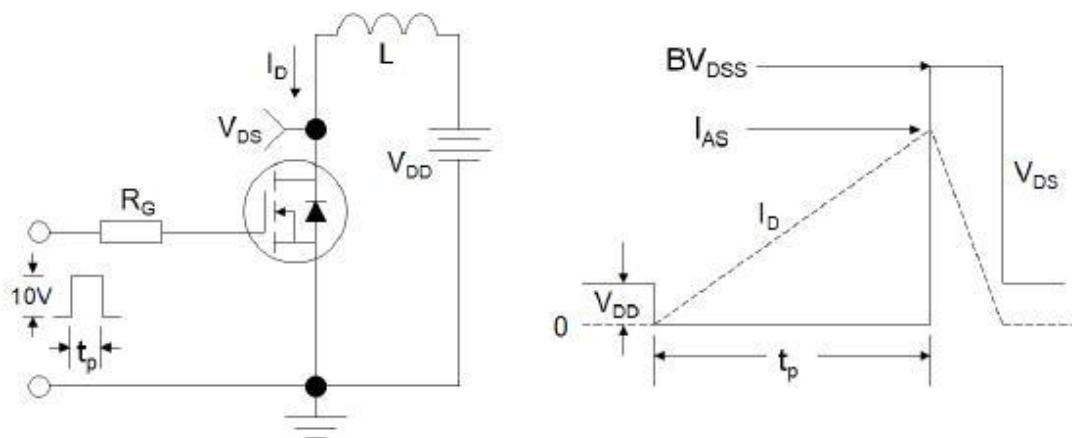
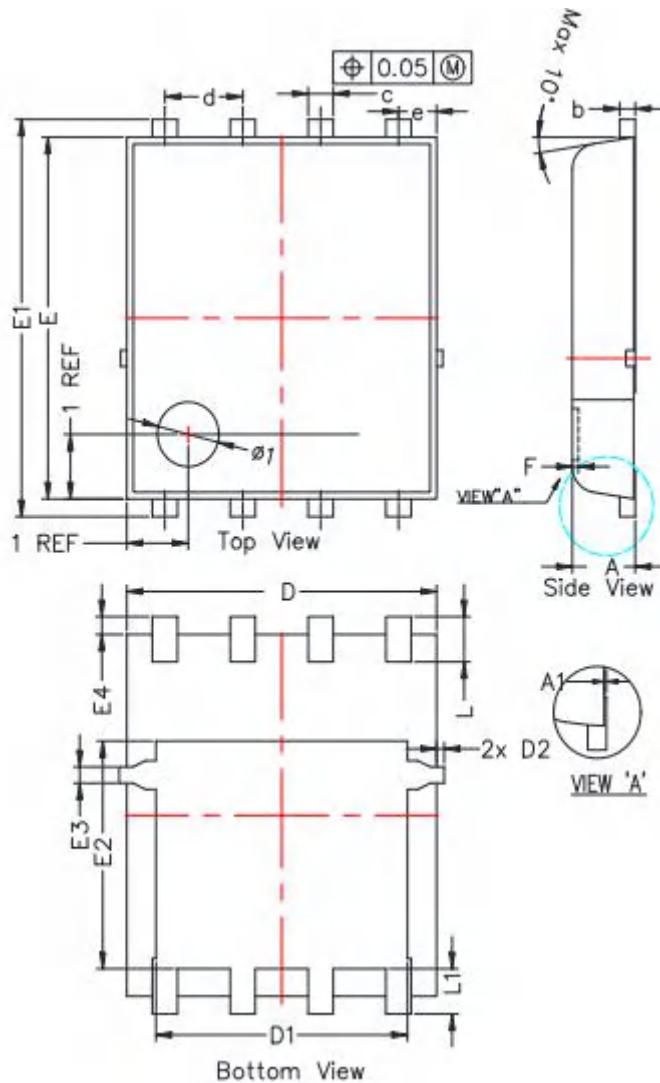


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data- PDFN5X6-8L



SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
* A	0.900	1.000	1.100	0.035	0.039	0.043
A1	0.000	---	0.050	0.000	---	0.002
h	0.246	0.254	0.312	0.010	0.010	0.012
* c	0.310	0.410	0.510	0.012	0.016	0.020
d	1.27 BSC			0.050 BSC		
* D	4.950	5.050	5.150	0.195	0.199	0.203
D1	4.000	4.100	4.200	0.157	0.161	0.165
* D2	---	---	0.125	---	---	0.005
e	0.62 BSC			0.024 BSC		
* E	5.500	5.600	5.700	0.217	0.220	0.224
* E1	6.050	6.150	6.250	0.238	0.242	0.246
E2	3.425	3.525	3.625	0.135	0.139	0.143
E3	0.150	0.250	0.350	0.006	0.010	0.014
* E4	0.175	0.275	0.375	0.007	0.011	0.015
F	-	-	0.100	-	-	0.004
* L	0.500	0.600	0.700	0.02	0.02	0.03
L1	0.600	0.700	0.800	0.02	0.03	0.03

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